

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-19 (Canceled).

Claim 20 (Currently Amended): A method of manufacturing a semiconductor substrate, the method comprising:

the a step of preparing a first substrate having a porous layer inside and a non-porous layer on the porous layer;

the a step of bonding the first substrate and a second substrate via the non-porous layer to form a bonded substrate stack; and

the a separation step of separating the bonded substrate stack into two substrates at the porous layer while rotating the bonded substrate stack about an axis perpendicular to the porous layer and ejecting a stream of fluid from an ejection portion and injecting the fluid into the porous layer,

wherein the separation step comprises the a peripheral portion separation step of separating a peripheral portion of the bonded substrate stack when in a state that a rotational direction of the bonded substrate stack, a moving direction of the fluid, and a position of said the ejection portion satisfy a condition in which the a moving direction component of the a velocity of the bonded substrate stack at an injection position of the fluid to the bonded substrate stack has a negative value.

Claim 21 (Currently Amended): A method of manufacturing a semiconductor substrate, the method comprising:

~~the a~~ step of preparing a first substrate having a porous layer inside and a non-porous layer on the porous layer;

~~the a~~ step of bonding the first substrate and a second substrate via the non-porous layer to form a bonded substrate stack; and

~~the a~~ separation step of separating the bonded substrate stack into two substrates at the porous layer while ejecting a stream of fluid and injecting the fluid into the porous layer, wherein the separation step comprises ~~the a~~ peripheral portion separation step of separating a peripheral portion of the bonded substrate stack under a condition in which an outermost peripheral portion of the bonded substrate stack is separated from an inside to an outside of the bonded substrate stack by the fluid injected into the bonded substrate stack.